

Mfg. composite material - by forming body from two metal tapes with powder- storing portion between them, then filling body with powder NoAbstract  
Patent Assignee: TANAKA DENSHI KOGYO KK

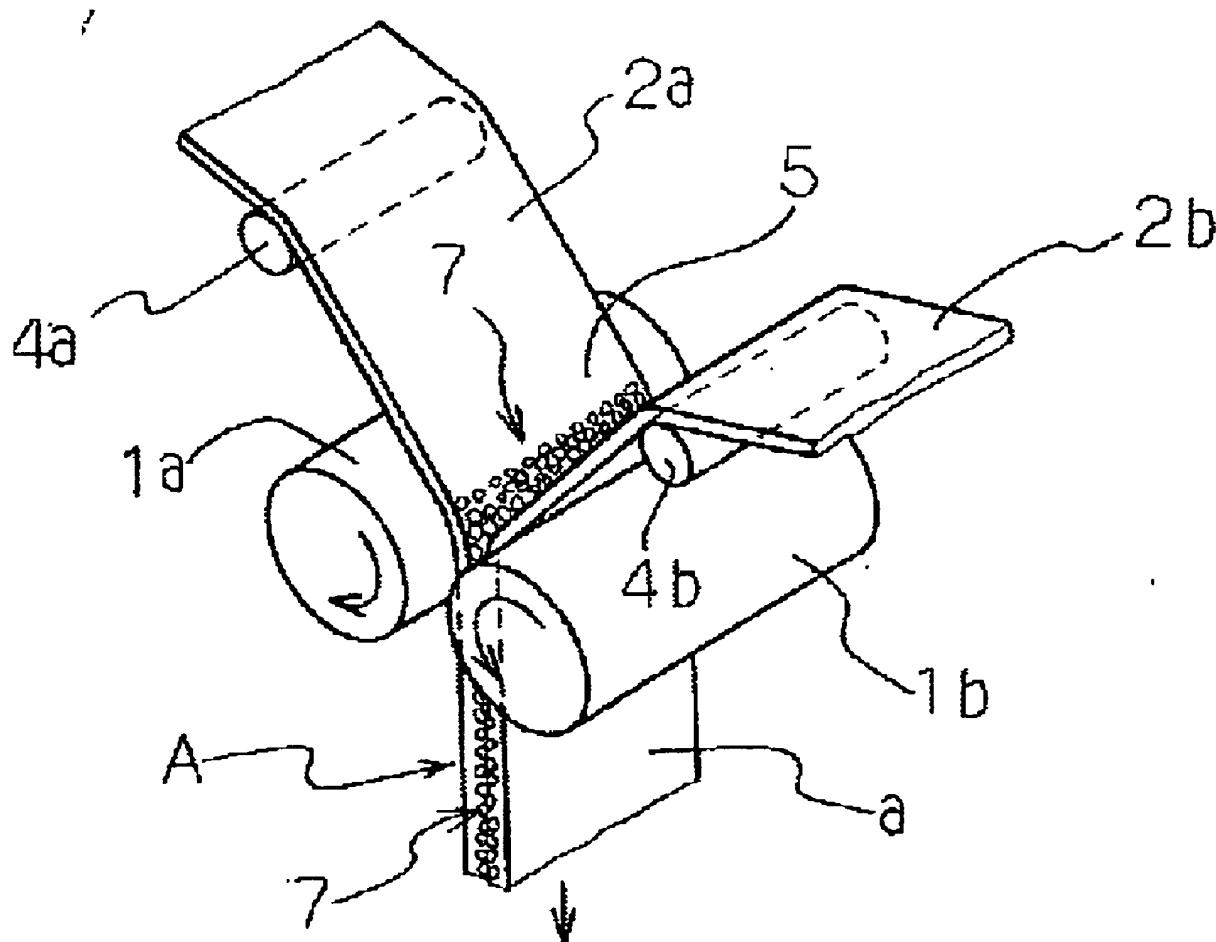
#### Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 6218580	A	19940809	JP 9311685	A	19930127	199436	B

Priority Applications (Number Kind Date): JP 9311685 A ( 19930127)

#### Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 6218580	A		7	B23K-035/40	



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Dialog® File Number 351 Accession Number 10022648

**Solder material mfr. of various shapes - by compression moulding silver, aluminium and copper into thin sheet**

**Patent Assignee: MEIDENSHA CORP**

#### Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 3032488	A	19910213	JP 89166466	A	19890628	199113	B
JP 2679268	B2	19971119	JP 89166446	A	19890628	199751	

**Priority Applications (Number Kind Date):** JP 89166446 A ( 19890628); JP 89166466 A ( 19890628)

#### Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 3032488	A		4		
JP 2679268	B2		3	B23K-035/40	Previous Publ. patent JP 3032488

#### Abstract:

JP 3032488 A

Process for mfg. a solder material of Ag, Al, and Cu, comprises compression moulding a powder mixt. contg. by wt., 25-80% Ag, 14-75% Al, and 1-30% Cu into a thin sheet.

Most pref., the solder material comprises by wt., 30-58% Ag, 26-60% Al, and 10-25% Cu, and the powder is classified to 100 mesh or under, with Al pref. comprising grains 20 microns or larger in dia..

**USE/ADVANTAGE** - Provides a thin sheet solder of desired shape (by readily machining with a C.G. a laser beam, having a low soldering temp. of ca. 650 deg.C and applicable to various materials not only Cu but also to Fe, stainless steel, Coval, Ti, Ni, etc.. (4pp Dwg.No.0/1)

Derwent World Patents Index

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Dialog® File Number 351 Accession Number 8585502